2SD1742, 2SD1742A

Silicon NPN triple diffusion planar type

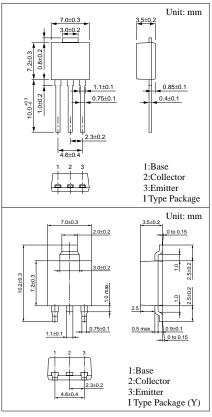
For low-freauency power amplification Complementary to 2SB1172 and 2SB1172A

Features

- \bullet High forward current transfer ratio $h_{F\!E}$ which has satisfactory linearity
- Low collector to emitter saturation voltage V_{CE(sat)}
- I type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment.

Absolute Maximum Ratings (T_C=25°C)

Parameter		Symbol	Ratings	Unit	
Collector to	2SD1742	V	60	V	
base voltage	2SD1742A	V_{CBO}	80		
Collector to	2SD1742	3.7	60	V	
emitter voltage	2SD1742A	V_{CEO}	80		
Emitter to base voltage		V_{EBO}	6	V	
Peak collector current		I_{CP}	5	A	
Collector current		I_{C}	3	A	
Collector power	T _C =25°C	n	15	***	
dissipation	Ta=25°C	P_{C}	1.3	W	
Junction temperature		T _j	150	°C	
Storage temperature		T_{stg}	-55 to +150	°C	



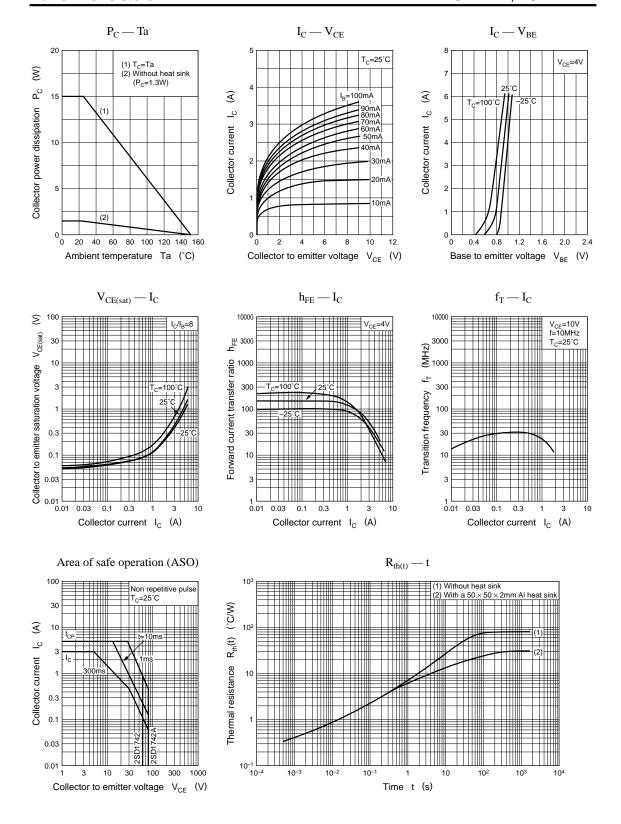
Electrical Characteristics ($T_C=25^{\circ}C$)

Parameter		Symbol	Conditions	min	typ	max	Unit
Collector cutoff	2SD1742		$V_{CE} = 60V, V_{BE} = 0$			200	μА
current	2SD1742A	I _{CES}	$V_{CE} = 80V, V_{BE} = 0$			200	
Collector cutoff	2SD1742	I _{CEO}	$V_{CE} = 30V, I_{B} = 0$			300	μА
current	2SD1742A		$V_{CE} = 60V, I_{B} = 0$			300	
Emitter cutoff current		I_{EBO}	$V_{EB} = 6V, I_C = 0$			1	mA
Collector to emitter	2SD1742	V _{CEO}	$I_{\rm C} = 30 {\rm mA}, I_{\rm B} = 0$	60			V
voltage	2SD1742A			80			
Forward current transfer ratio		h _{FE1} *	$V_{CE} = 4V, I_C = 1A$	70		250	
		h _{FE2}	$V_{CE} = 4V, I_C = 3A$	10			
Base to emitter voltage		V _{BE}	$V_{CE} = 4V, I_C = 3A$			1.8	V
Collector to emitter saturation voltage		V _{CE(sat)}	$I_C = 3A, I_B = 0.375A$			1.2	V
Transition frequency		f_{T}	$V_{CE} = 10V, I_{C} = 0.5A, f = 10MHz$		30		MHz
Turn-on time		t _{on}	$I_C = 1A, I_{B1} = 0.1A, I_{B2} = -0.1A,$		0.5		μs
Storage time		t _{stg}			2.5		μs
Fall time		t _f	$V_{CC} = 50V$		0.4		μs

*h_{FE1} Rank classification

Rank	Q	P		
h_{FE1}	70 to 150	120 to 250		

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